

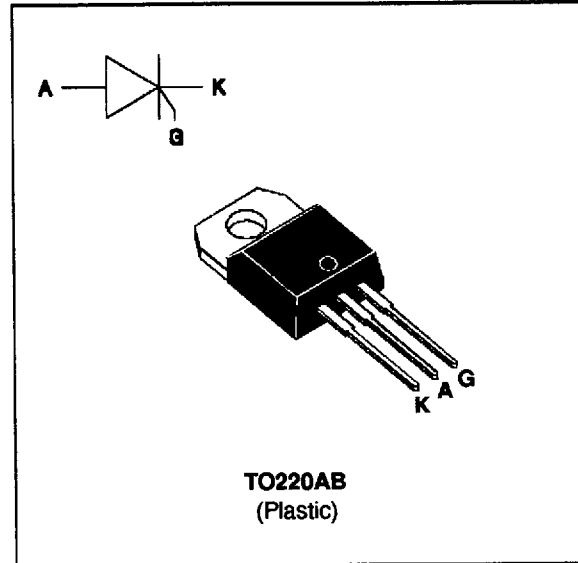


**FEATURES**

- HIGH SURGE CAPABILITY
- HIGH ON-STATE CURRENT
- HIGH STABILITY AND RELIABILITY
- TXN Serie :  
INSULATED VOLTAGE = 2500V<sub>(RMS)</sub>  
(UL RECOGNIZED : E81734)

**DESCRIPTION**

The TYN/TXN 058 ---> TYN/TXN 1008 Family of Silicon Controlled Rectifiers uses a high performance glass passivated chips technology. This general purpose Family of Silicon Controlled Rectifiers is designed for power supplies up to 400Hz on resistive or inductive load.



**ABSOLUTE RATINGS (limiting values)**

Symbol	Parameter		Value	Unit
$I_T(RMS)$	RMS on-state current (180° conduction angle)	TXN Tc=100°C TYN Tc=105°C	8	A
$I_T(AV)$	Average on-state current (180° conduction angle, single phase circuit)	TXN Tc=100°C TYN Tc=105°C	5	A
$I_{TSM}$	Non repetitive surge peak on-state current ( $T_j$ initial = 25°C)	$t_p=8.3$ ms	84	A
		$t_p=10$ ms	80	
$i^2t$	$i^2t$ value	$t_p=10$ ms	32	A <sup>2</sup> s
$di/dt$	Critical rate of rise of on-state current Gate supply : $I_G = 100$ mA $di_G/dt = 1$ A/ $\mu$ s		50	A/ $\mu$ s
$T_{stg}$ $T_j$	Storage and operating junction temperature range		- 40 to + 150 - 40 to + 125	°C °C
$T_l$	Maximum lead temperature for soldering during 10 s at 4.5 mm from case		260	°C

Symbol	Parameter	TYN/TXN							Unit
		058	108	208	408	608	808	1008	
$V_{DRM}$ $V_{RRM}$	Repetitive peak off-state voltage $T_j = 125$ °C	50	100	200	400	600	800	1000	V

**THERMAL RESISTANCES**

Symbol	Parameter	Value	Unit
Rth (j-a)	Junction to ambient	60	°C/W
Rth (j-c) DC	Junction to case for DC	TXN	3.5
		TYN	2.5

**GATE CHARACTERISTICS (maximum values)**

PG (AV) = 1W PGM = 10W (tp = 20 μs) IFGM = 4A (tp = 20 μs) VRGM = 5 V.

**ELECTRICAL CHARACTERISTICS**

Symbol	Test Conditions			Value		Unit
				BLANK	G	
IGT	VD=12V (DC) RL=33Ω	Tj=25°C	MAX	15	25	mA
VGT	VD=12V (DC) RL=33Ω	Tj=25°C	MAX	1.5		V
VGD	VD=VDRM RL=3.3kΩ	Tj= 110°C	MIN	0.2		V
tgt	VD=VDRM IG = 40mA dIG/dt = 0.5A/μs	Tj=25°C	TYP	2		μs
IL	IG= 1.2 IGT	Tj=25°C	TYP	50		mA
IH	IT= 100mA gate open	Tj=25°C	MAX	30	45	mA
VTM	ITM= 16A tp= 380μs	Tj=25°C	MAX	1.8		V
IDRM IRRM	VDRM Rated VRRM Rated	Tj=25°C	MAX	0.01		mA
		Tj= 110°C		2		
dV/dt	Linear slope up to VD=67%VDRM gate open	Tj= 110°C	MIN	200	500	V/μs
tq	VD=67%VDRM ITM= 16A VR= 25V dITM/dt=30 A/μs dVD/dt= 50V/μs	Tj= 110°C	TYP	70		μs

Package	$I_{T(RMS)}$	$V_{DRM} / V_{RRM}$	Sensitivity Specification	
	A	V	BLANK	G
TXN (Insulated)	8	50	X	X
		100	X	X
		200	X	X
		400	X	X
		600	X	X
		800	X	X
		1000	X	X
TYN (Uninsulated)	8	50	X	X
		100	X	X
		200	X	X
		400	X	X
		600	X	X
		800	X	X
		1000	X	X

Fig.1 : Maximum average power dissipation versus average on-state current (TXN).

Fig.2 : Correlation between maximum average power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact (TXN).

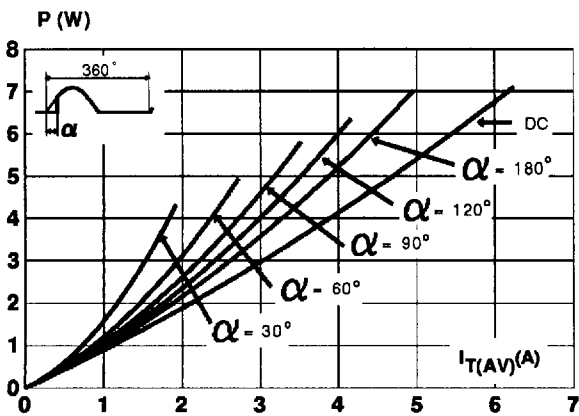


Fig.3 : Maximum average power dissipation versus average on-state current (TYN).

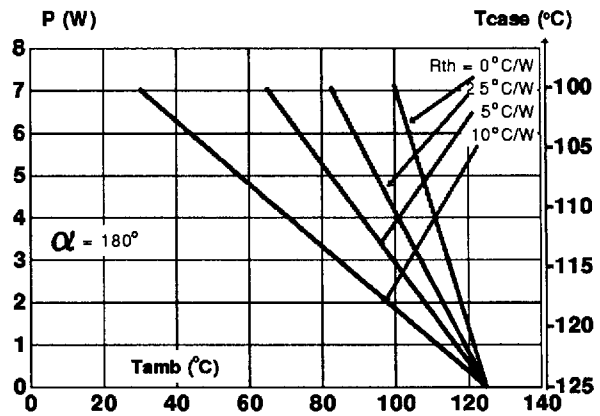
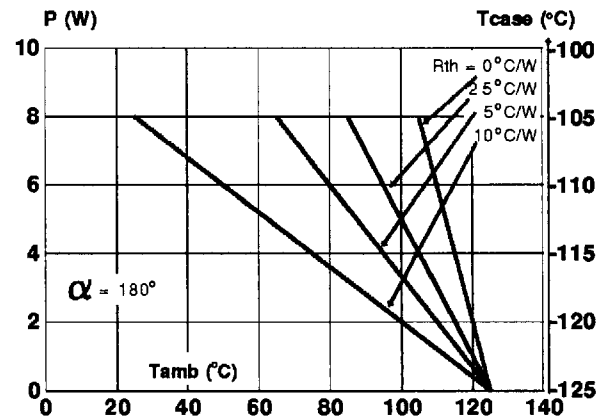
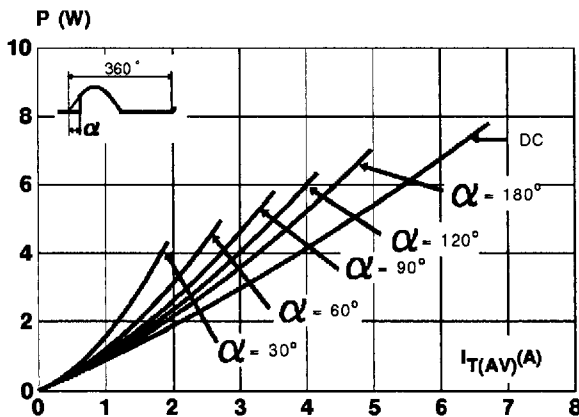


Fig.4 : Correlation between maximum average power dissipation and maximum allowable temperatures ( $T_{amb}$  and  $T_{case}$ ) for different thermal resistances heatsink + contact (TYN).



TXN/TYN 058 (G) ---> TXN/TYN 1008 (G)

Fig.5 : Average on-state current versus case temperature (TXN).

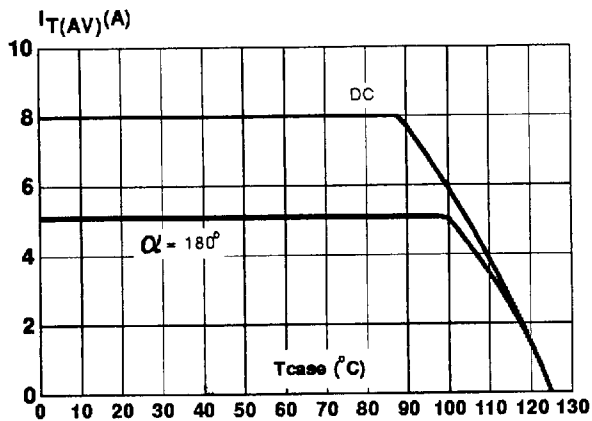


Fig.6 : Average on-state current versus case temperature (TYN).

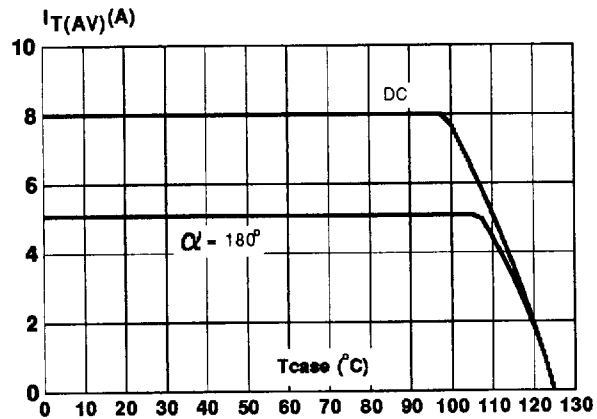


Fig.7 : Relative variation of thermal impedance versus pulse duration.

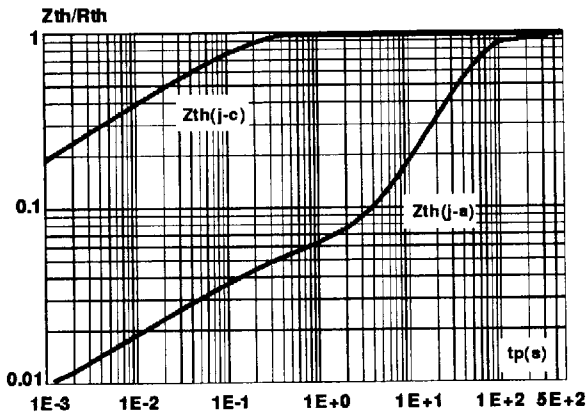


Fig.8 : Relative variation of gate trigger current versus junction temperature.

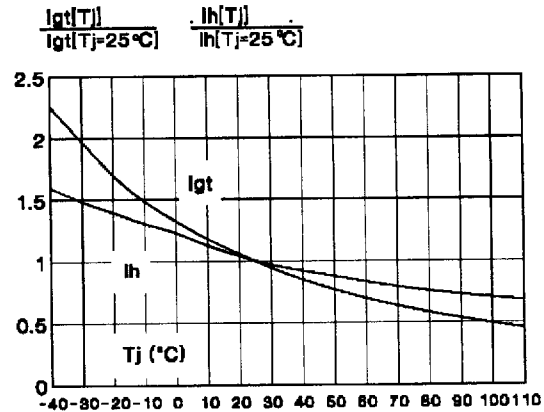


Fig.9 : Non repetitive surge peak on-state current versus number of cycles.

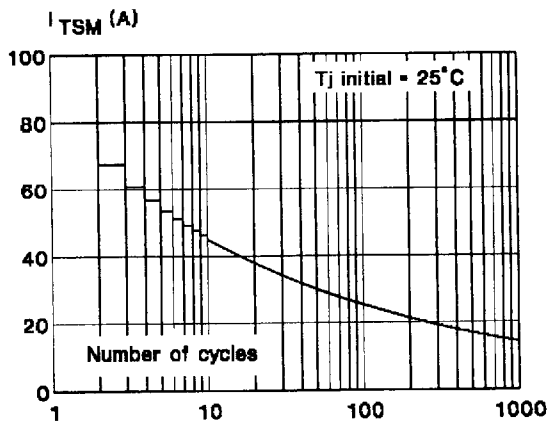


Fig.10 : Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t \leq 10$  ms, and corresponding value of  $I^2t$ .

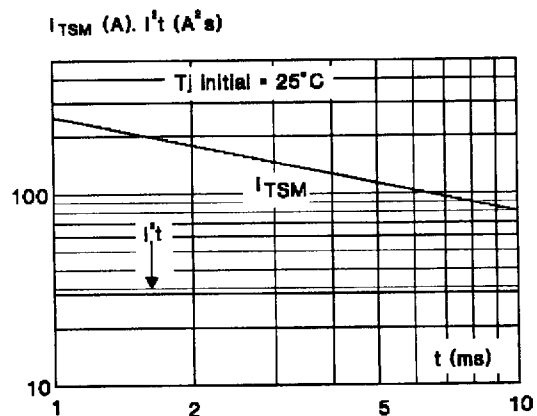
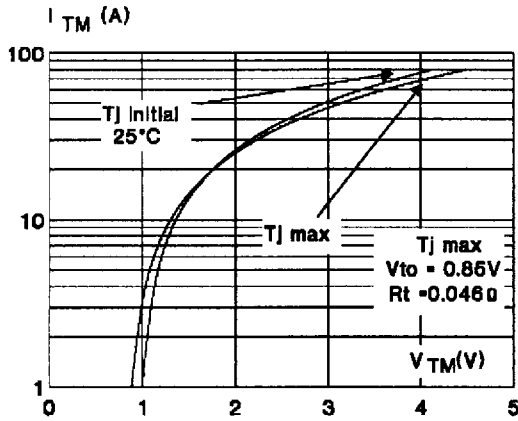
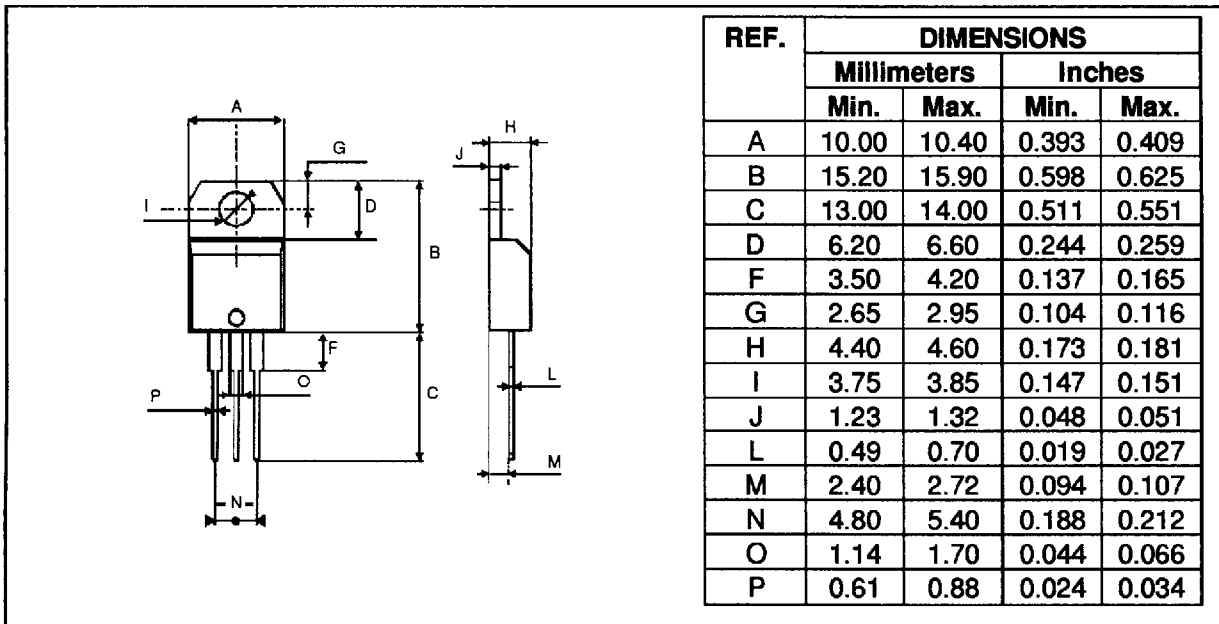


Fig.11 : On-state characteristics (maximum values).



**PACKAGE MECHANICAL DATA**

TO220AB Plastic



Cooling method : C  
 Marking : type number  
 Weight : 2.3 g

Recommended torque value : 0.8 m.N.  
 Maximum torque value : 1 m.N.

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